

### N and P-Channel Enhancement Mode Power MOSFET

### **Description**

The NCE2003 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

### **General Features**

#### N-Channel

 $V_{DS}$  = 20V, $I_D$  =3A

 $R_{DS(ON)}$  < 45m $\Omega$  @  $V_{GS}$ =4.5V

 $R_{DS(ON)}$  < 60m $\Omega$  @  $V_{GS}$ =2.5V

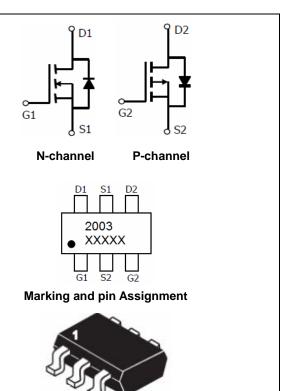
### P-Channel

 $V_{DS} = -20V, I_{D} = -3A$ 

 $R_{DS(ON)} < 110 m\Omega @ V_{GS} = -4.5 V$ 

 $R_{DS(ON)}$  < 140m $\Omega$  @  $V_{GS}$ =-2.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package



SOT-23-6L top view

**Package Marking and Ordering Information** 

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2003	NCE2003	SOT-23-6L	Ø180mm	8mm	3000 units

Absolute Maximum Ratings (T<sub>A</sub>=25 ℃unless otherwise noted)

Param	Symbol	N-Channel	P-Channel	nel Unit		
Drain-Source Voltage	V <sub>DS</sub>	20	-20			
Gate-Source Voltage	V <sub>GS</sub>	±12	±12	V		
Continuous Drain Corrent	T <sub>A</sub> =25℃		3	-3	۸	
Continuous Drain Current	T <sub>A</sub> =70°C	I <sub>D</sub>	2.4	-2.4	Α	
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	13	-13	Α	
Maximum Power Dissipation T <sub>A</sub> =25℃		P <sub>D</sub>	0.8	0.8	W	
Operating Junction and Storage	$T_{J}$ , $T_{STG}$	-55 To 150	-55 To 150	$^{\circ}$		

### **Thermal Characteristic**

Thermal Resistance,Junction-to-Ambient (Note2)	$R_{\theta JA}$	N-Ch	156	°C/W
Thermal Resistance,Junction-to-Ambient (Note2)	$R_{\theta JA}$	P-Ch	156	°C/W



## N-CH Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit	
Off Characteristics							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	20	22	-	V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =20V,V <sub>GS</sub> =0V	-	-	1	μA	
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA	
On Characteristics (Note 3)			•				
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	0.5	0.75	1.2	V	
Drain-Source On-State Resistance	В	V <sub>GS</sub> =2.5V, I <sub>D</sub> =3A	-	35	60	mΩ	
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	-	29	45	mΩ	
Forward Transconductance	<b>g</b> FS	$V_{DS}$ =5 $V$ , $I_{D}$ =3 $A$	-	8	-	S	
Dynamic Characteristics (Note4)							
Input Capacitance	C <sub>lss</sub>	\/ -40\/\/ -0\/	-	260	-	PF	
Output Capacitance	Coss	$V_{DS}$ =10V, $V_{GS}$ =0V, F=1.0MHz	-	48	-	PF	
Reverse Transfer Capacitance	C <sub>rss</sub>	F-1.0MHZ	-	27	-	PF	
Switching Characteristics (Note 4)							
Turn-on Delay Time	t <sub>d(on)</sub>		-	2.5	-	nS	
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =10V, $R_L$ =3.3 $\Omega$	-	3.2	-	nS	
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =4.5 $V$ , $R_{GEN}$ =6 $\Omega$	-	21	-	nS	
Turn-Off Fall Time	t <sub>f</sub>		-	3	-	nS	
Total Gate Charge	Qg	\/ -40\/   -24	-	2.9	5	nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =10V, $I_{D}$ =3A, $V_{GS}$ =4.5V	-	0.4	-	nC	
Gate-Drain Charge	$Q_{gd}$	v <sub>GS</sub> -4.5v	-	0.6	-	nC	
Drain-Source Diode Characteristics	•		•				
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =3 A	-	-	1.2	V	
Diode Forward Current (Note 2)	Is		-	-	3	Α	

### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



## P-CH Electrical Characteristics (TA=25 ℃unless otherwise noted

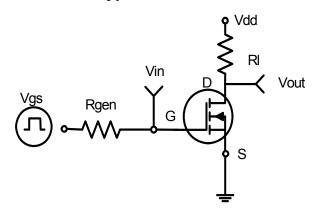
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-20		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-20V,V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-0.4	-0.7	-1	V
Dunin Course On Otata Registeres	Б	$V_{GS}$ =-4.5V, $I_D$ =-3A	-	78	110	mΩ
Drain-Source On-State Resistance	$R_{DS(ON)}$	V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-2A	-	102	140	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-5V,I <sub>D</sub> =-3A	-	9.5	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>	\/ - 40\/\/ -0\/	-	325	-	PF
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ =-10V, $V_{GS}$ =0V, F=1.0MHz	-	63	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	r-1.0ivinz	-	37	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	11	-	nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =-10V, $R_L$ =5 $\Omega$	-	5.5	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-4.5 $V$ , $R_{GEN}$ =3 $\Omega$	-	22	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	8	-	nS
Total Gate Charge	Qg	\/ - 40\/   - 24	-	3.2	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =-10V, $I_{D}$ =-3A, $V_{GS}$ =-4.5V	-	0.6	-	nC
Gate-Drain Charge	$Q_{gd}$	v <sub>GS</sub> =-4.5v	-	0.9	-	nC
Drain-Source Diode Characteristics			•		-	
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	$V_{GS}$ =0 $V$ , $I_{S}$ =-3 $A$	-	-	-1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	-3	Α

### Notes:

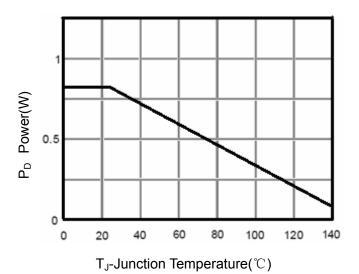
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



### N- Channel Typical Electrical and Thermal Characteristics (Curves)



**Figure 1:Switching Test Circuit** 



**Figure 3 Power Dissipation** 

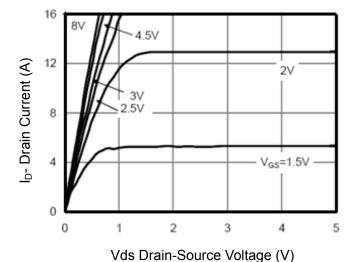


Figure 5 Output Characteristics

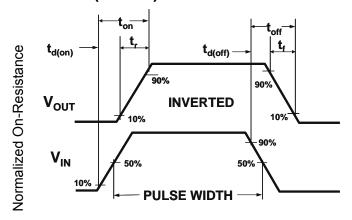
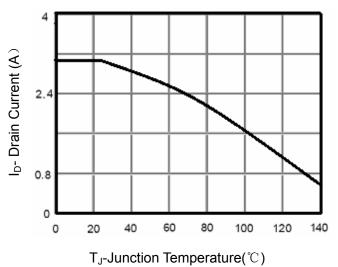
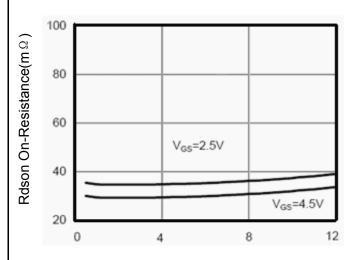


Figure 2:Switching Waveforms

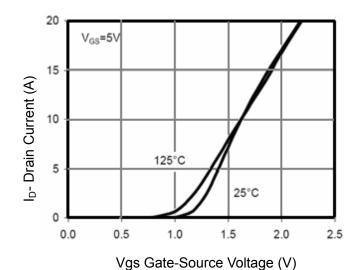


**Figure 4 Drain Current** 

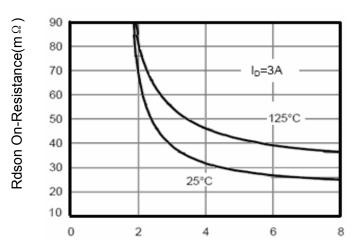


I<sub>D</sub>- Drain Current (A) **Figure 6 Drain-Source On-Resistance** 





**Figure 7 Transfer Characteristics** 



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

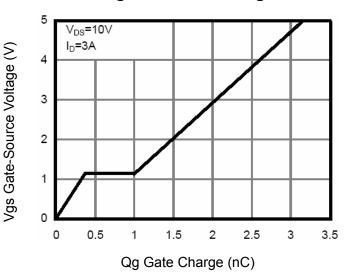


Figure 11 Gate Charge

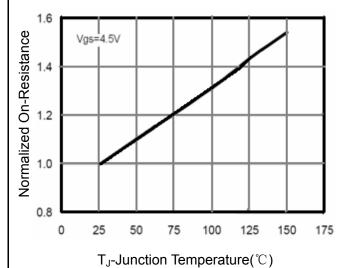


Figure 8 Drain-Source On-Resistance

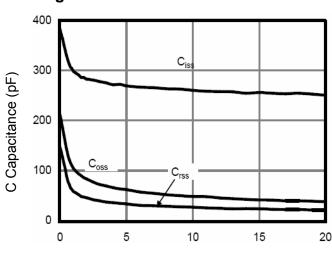
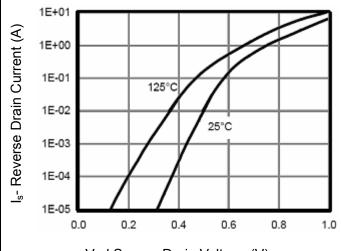


Figure 10 Capacitance vs Vds

Vds Drain-Source Voltage (V)



Vsd Source-Drain Voltage (V)

Figure 12 Source- Drain Diode Forward



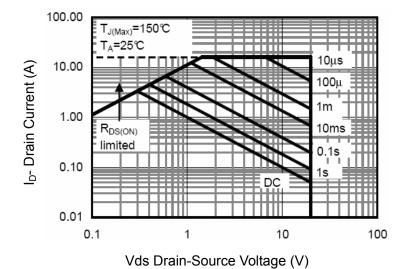
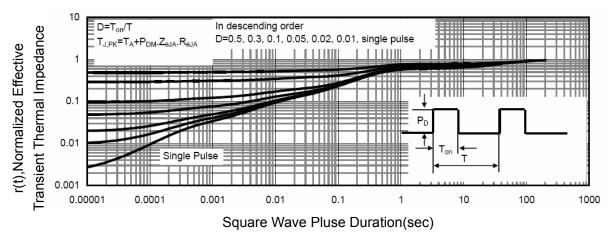


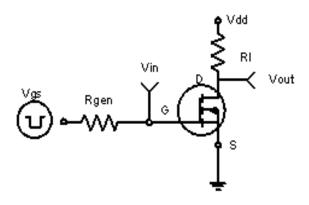
Figure 13 Safe Operation Area



**Figure 14 Normalized Maximum Transient Thermal Impedance** 



### P- Channel Typical Electrical and Thermal Characteristics (Curves)



**Figure 1:Switching Test Circuit** 

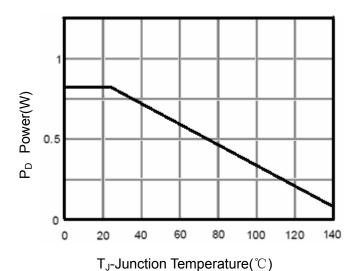
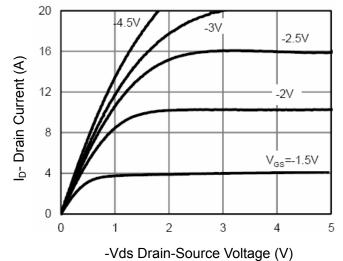


Figure 3 Power Dissipation



**Figure 5 Output Characteristics** 

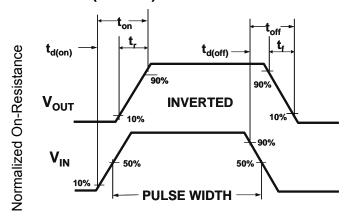
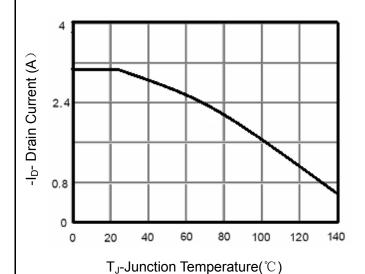


Figure 2:Switching Waveforms



**Figure 4 Drain Current** 

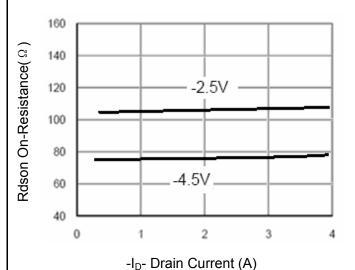
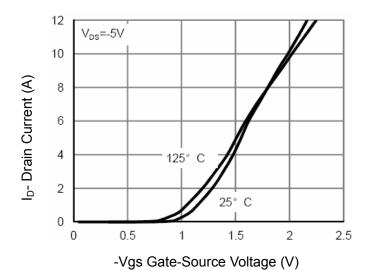


Figure 6 Drain-Source On-Resistance





**Figure 7 Transfer Characteristics** 

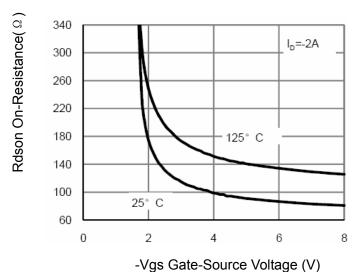


Figure 9 Rdson vs Vgs

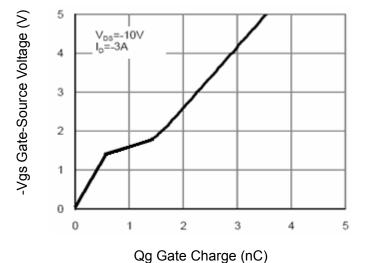
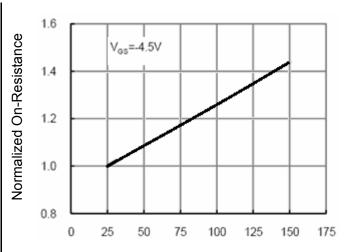


Figure 11 Gate Charge



 $T_J$ -Junction Temperature( ${}^{\circ}$ C) Figure 8 Drain-Source On-Resistance

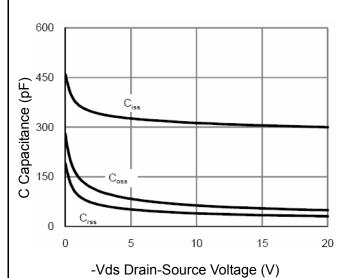


Figure 10 Capacitance vs Vds

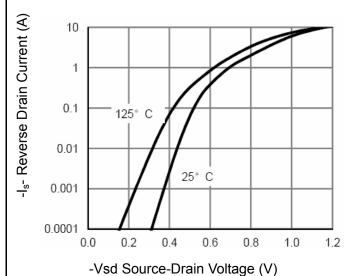
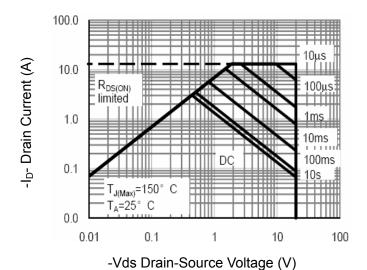
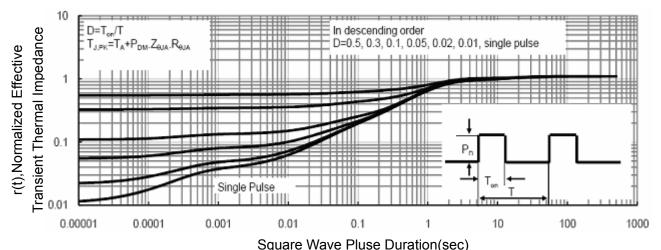


Figure 12 Source- Drain Diode Forward





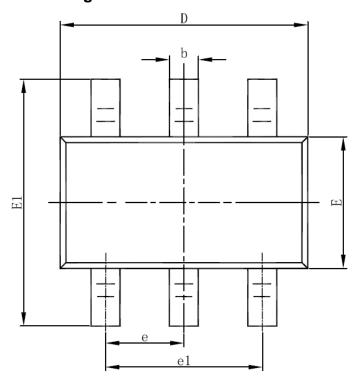
**Figure 13 Safe Operation Area** 

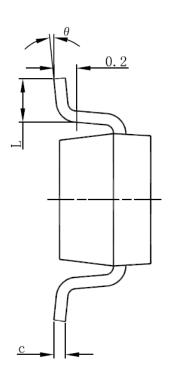


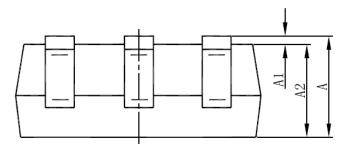
Square Wave Pluse Duration(sec)
Figure 14 Normalized Maximum Transient Thermal Impedance



# **SOT23-6L Package Information**







Cl	Dimensions Ir	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
А	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950(BSC)		0.037(BSC)		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



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